

# Simon Vigonski

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/3759754/publications.pdf>

Version: 2024-02-01

12  
papers

102  
citations

1684188

5  
h-index

1372567

10  
g-index

12  
all docs

12  
docs citations

12  
times ranked

115  
citing authors

#	ARTICLE	IF	CITATIONS
1	Mechanism of Spontaneous Surface Modifications on Polycrystalline Cu Due to Electric Fields. <i>Micromachines</i> , 2021, 12, 1178.	2.9	1
2	Data sets and trained neural networks for Cu migration barriers. <i>Data in Brief</i> , 2020, 32, 106094.	1.0	1
3	Growth mechanism for nanotips in high electric fields. <i>Nanotechnology</i> , 2020, 31, 355301.	2.6	19
4	Application of artificial neural networks for rigid lattice kinetic Monte Carlo studies of Cu surface diffusion. <i>Computational Materials Science</i> , 2020, 183, 109789.	3.0	8
5	Tungsten migration energy barriers for surface diffusion: a parameterization for KMC simulations. <i>Modelling and Simulation in Materials Science and Engineering</i> , 2020, 28, 035011.	2.0	4
6	The effect of heat treatment on the morphology and mobility of Au nanoparticles. <i>Beilstein Journal of Nanotechnology</i> , 2020, 11, 61-67.	2.8	4
7	Migration barriers for surface diffusion on a rigid lattice: Challenges and solutions. <i>Computational Materials Science</i> , 2018, 146, 287-302.	3.0	21
8	Data sets of migration barriers for atomistic Kinetic Monte Carlo simulations of Fe self-diffusion. <i>Data in Brief</i> , 2018, 19, 564-569.	1.0	0
9	Data sets of migration barriers for atomistic Kinetic Monte Carlo simulations of Cu self-diffusion via first nearest neighbour atomic jumps. <i>Data in Brief</i> , 2018, 17, 739-743.	1.0	2
10	Au nanowire junction breakup through surface atom diffusion. <i>Nanotechnology</i> , 2018, 29, 015704.	2.6	27
11	Molecular dynamics simulations of near-surface Fe precipitates in Cu under high electric fields. <i>Modelling and Simulation in Materials Science and Engineering</i> , 2015, 23, 025009.	2.0	10
12	Verification of a multiscale surface stress model near voids in copper under the load induced by external high electric field. <i>Applied Mathematics and Computation</i> , 2015, 267, 476-486.	2.2	5